

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –
Part 20-1: Handling, packing, labelling and shipping of surface-mount devices
sensitive to the combined effect of moisture and soldering heat**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –
Partie 20-1: Manipulation, emballage, étiquetage et transport des composants
pour montage en surface sensibles à l'effet combiné de l'humidité et de la
chaleur de brasage**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 20-1: Handling, packing, labelling and shipping of surface-mount
devices sensitive to the combined effect of moisture and soldering heat**

FOREWORD

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This second edition cancels and replaces the first edition published in 2009. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) updates to subclauses to better align the test method with IPC/JEDEC J-STD-033C, including new sections on aqueous cleaning and dry pack precautions;
- b) addition of two annexes on colorimetric testing of HIC (humidity indicator card) and derivation of bake tables.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2565/FDIS	47/2579/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

The advent of surface-mount devices (SMDs) introduced a new class of quality and reliability concerns regarding package damage "cracks and delamination" from the solder reflow process. This document describes the standardized levels of floor life exposure for moisture/reflow-sensitive SMDs along with the handling, packing and shipping requirements necessary to avoid moisture/reflow-related failures. IEC 60749-20 defines the classification procedure and Annex A of this document defines the labelling requirements.

Moisture from atmospheric humidity enters permeable packaging materials by diffusion. Assembly processes used to solder SMDs to printed circuit boards (PCBs) expose the entire package body to temperatures higher than 200 °C. During solder reflow, the combination of rapid moisture expansion, materials mismatch, and material interface degradation can result in package cracking and/or delamination of critical interfaces within the package.

Typical solder reflow processes of concern for all devices are infrared (IR), convection/IR, convection, vapour phase reflow (VPR), hot air rework tools, and wave solder, including full immersion.

Non-semiconductor devices can exhibit additional process sensitivities beyond moisture sensitivity such as thermal sensitivity, flux sensitivity, or cleaning process sensitivity.

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat

1 Scope

This part of IEC 60749 applies to all devices subjected to bulk solder reflow processes during PCB assembly, including plastic encapsulated packages, process sensitive devices, and other moisture-sensitive devices made with moisture-permeable materials (epoxies, silicones, etc.) that are exposed to the ambient air.

The purpose of this document is to provide SMD manufacturers and users with standardized methods for handling, packing, shipping, and use of moisture/reflow sensitive SMDs that have been classified to the levels defined in IEC 60749-20. These methods are provided to avoid damage from moisture absorption and exposure to solder reflow temperatures that can result in yield and reliability degradation. By using these procedures, safe and damage-free reflow can be achieved, with the dry packing process, providing a minimum shelf life capability in sealed dry-bags from the seal date.

Two test conditions, method A and method B, are specified in the soldering heat test of IEC 60749-20. For method A, moisture soak conditions are specified on the assumption that moisture content inside the moisture barrier bag is less than 30 % RH. For method B, moisture soaking conditions are specified on the assumption that manufacturer's exposure time (MET) does not exceed 24 h and the moisture content inside the moisture barrier bag is less than 10 % RH. In an actual handling environment, SMDs tested by method A are permitted to absorb moisture up to 30 % RH, and SMDs tested by method B are permitted to absorb moisture up to 10 % RH. This document specifies the handling conditions for SMDs subjected to the above test conditions.

NOTE Hermetic SMD packages are not moisture sensitive and do not require moisture precautionary handling.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60749-20, *Semiconductor devices – Mechanical and climatic test methods – Part 20: Resistance of plastic-encapsulated SMDs to the combined effect of moisture and soldering heat*

IEC 60749-30, *Semiconductor devices – Mechanical and climatic test methods – Part 30: Preconditioning of non-hermetic surface mount devices prior to reliability testing*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

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